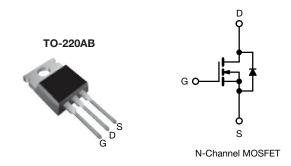
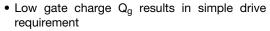


Power MOSFET



PRODUCT SUMMARY					
V _{DS} (V)	500				
$R_{DS(on)}(\Omega)$	V _{GS} = 10 V	3.0			
Q _g (Max.) (nC)	17				
Q _{gs} (nC)	4.3				
Q _{gd} (nC)	8.5				
Configuration	Single				

FEATURES





- Improved gate, avalanche and dynamic dV/dt ruggedness
- Fully characterized capacitance and avalanche voltage and current
- Effective C_{oss} specified
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

Note

* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

APPLICATIONS

- Switch mode power supply (SMPS)
- Uninterruptable power supply
- · High speed power switching

TYPICAL SMPS TOPOLOGIES

- · Two transistor forward
- Half bridge
- Full bridge

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free	IRF820APbF
Lead (Pb)-free and halogen-free	IRF820APbF-BE3

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise parameter			SYMBOL	LIMIT	UNIT	
				500	ONIT	
Drain-source voltage			V _{DS}		V	
Gate-source voltage			V_{GS}	± 30		
Continuous drain current	V _{GS} at 10 V	$T_{\rm C} = 25 ^{\circ}{\rm C}$ $T_{\rm C} = 100 ^{\circ}{\rm C}$	- I _D	2.5		
		T _C = 100 °C		1.6	Α	
Pulsed drain current ^a			I _{DM}	10		
Linear derating factor				0.40	W/°C	
Single pulse avalanche energy b			E _{AS}	140	mJ	
Repetitive avalanche current a			I _{AR}	2.5	Α	
Repetitive avalanche energy ^a			E _{AR}	5.0	mJ	
Maximum power dissipation	T _C = 25 °C		P_{D}	50	W	
Peak diode recovery dV/dt c			dV/dt	3.4	V/ns	
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +150	°C	
Soldering recommendations (peak temperature) d	For	10 s		300 ^d		
Mounting torque	6-32 or M3 screw			10	lbf ⋅ in	
				1.1	N · m	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Starting T_J = 25 °C, L = 45 mH, R_g = 25 $\Omega,\,I_{AS}$ = 2.5 A (see fig. 12)
- c. $I_{SD} \le 2.5 \text{ A}$, $dI/dt \le 270 \text{ A/}\mu\text{s}$, $V_{DD} \le V_{DS}$, $T_J \le 150 \,^{\circ}\text{C}$
- d. 1.6 mm from case



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THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R _{thJA}	-	62	
Case-to-sink, flat, greased surface	R _{thCS}	0.50	-	°C/W
Maximum junction-to-case (drain)	R _{thJC}	-	2.5	

SPECIFICATIONS (T _J = 25 °C, t	ınless otherw	ise noted)					
PARAMETER	SYMBOL	TEST	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0$	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference t	to 25 °C, I _D = 1 mA	-	0.60	-	V/°C
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V$	_{GS} , I _D = 250 μA	2.0	-	4.5	V
Gate-source leakage	I _{GSS}	V _G	_S = ± 30 V	-	-	± 100	nA
Zana anta malta an dunin annuant	I _{DSS}	$V_{DS} = 5$	V _{DS} = 500 V, V _{GS} = 0 V		-	25	
Zero gate voltage drain current		V _{DS} = 400 V, V	/ _{GS} = 0 V, T _J = 125 °C	-	-	250	μA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 1.5 A ^b	-	-	3.0	Ω
Forward transconductance	9 _{fs}	$V_{DS} = 5$	0 V, I _D = 1.5 A ^b	1.4	-	-	S
Dynamic							
Input capacitance	C _{iss}	V - 0 V		-	340	-	pF
Output capacitance	C _{oss}	V _I	$V_{GS} = 0 \text{ V},$ $V_{DS} = 25 \text{ V},$		53	-	
Reverse transfer capacitance	C _{rss}	$f = 1.0 \text{ MHz, see fig. 5}$ $V_{GS} = 0 \text{ V; } V_{DS} = 1.0 \text{ V, f} = 1.0 \text{ MHz}$ $V_{GS} = 0 \text{ V; } V_{DS} = 400 \text{ V, f} = 1.0 \text{ MHz}$ $V_{GS} = 0 \text{ V; } V_{DS} = 0 \text{ V to } 400 \text{ V}^c$		-	2.7	-	
Output capacitance	C _{oss}				490		
Output capacitance	C _{oss}				15		
Effective output capacitance	C _{oss} eff.				28		
Total gate charge	Q_g			-	-	17	
Gate-source charge	Q_{gs}	$V_{GS} = 10 \text{ V}$ $I_D = 2.5 \text{ A}, V_{DS} = 400 \text{ V},$ see fig. 6 and 13 ^b	-	-	4.3	nC	
Gate-drain charge	Q_{gd}		see lig. o and 15	-	-	8.5	1
Turn-on delay time	t _{d(on)}			-	8.1	-	- ns
Rise time	t _r	V 21	V 250 V L 2.5 A		12	-	
Turn-Off delay time	t _{d(off)}	V_{DD} = 250 V, I_D = 2.5 A, R_g = 21 Ω , R_D = 97 Ω , see fig. 10 ^b		-	16	-	
Fall time	t _f			-	13	-	
Drain-Source Body Diode Characteristic	cs				•	•	,
Continuous source-drain diode current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	2.5	- A
Pulsed diode forward current ^a	I _{SM}			-	-	10	
Body diode voltage	V_{SD}	$T_J = 25 ^{\circ}\text{C}, I_S = 2.5 \text{A}, V_{GS} = 0 \text{V}^{\text{b}}$		-	-	1.6	V
Body diode reverse recovery time	t _{rr}	T _J = 25 °C, I _F = 2.5 A, dI/dt = 100 A/μs ^b		-	330	500	ns
Body diode reverse recovery charge	Q _{rr}			-	760	1140	nC
Forward turn-on time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L _S and L				L _D)	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Pulse width \leq 300 µs; duty cycle \leq 2 %
- c. C_{oss} eff. is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

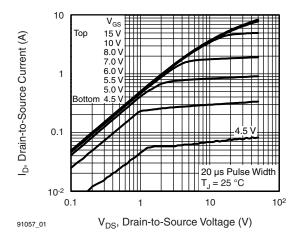


Fig. 1 - Typical Output Characteristics, $T_C = 25$ °C

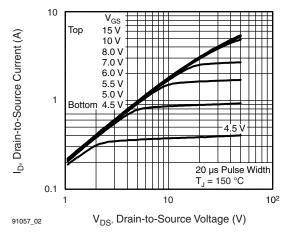


Fig. 2 - Typical Output Characteristics, $T_C = 150$ °C

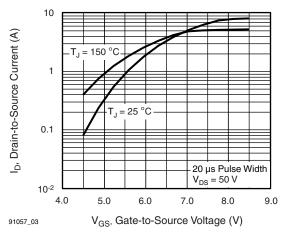


Fig. 3 - Typical Transfer Characteristics

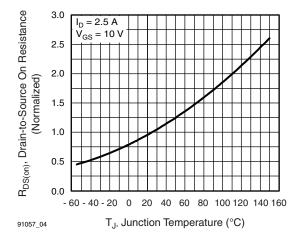


Fig. 4 - Normalized On-Resistance vs. Temperature

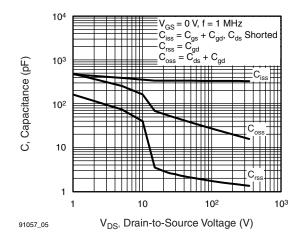


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

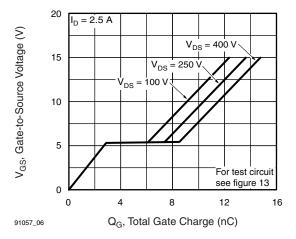


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



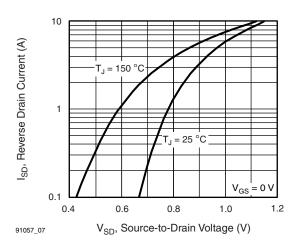


Fig. 7 - Typical Source-Drain Diode Forward Voltage

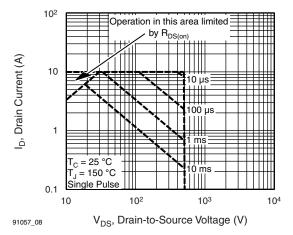


Fig. 8 - Maximum Safe Operating Area

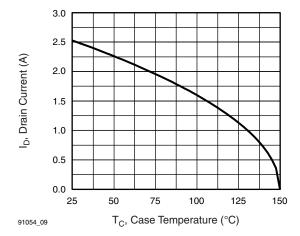


Fig. 9 - Maximum Drain Current vs. Case Temperature

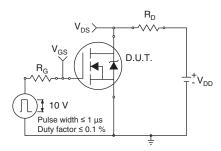


Fig. 10 - Switching Time Test Circuit

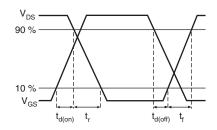


Fig. 11 - Switching Time Waveforms



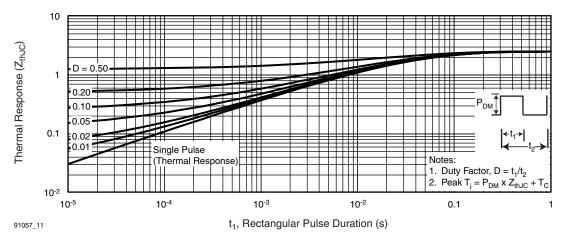


Fig. 12 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

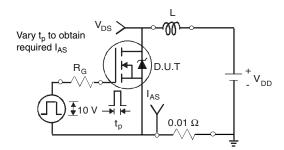


Fig. 13 - Unclamped Inductive Test Circuit

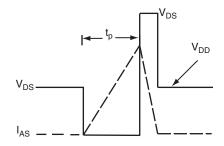


Fig. 14 - Unclamped Inductive Waveforms

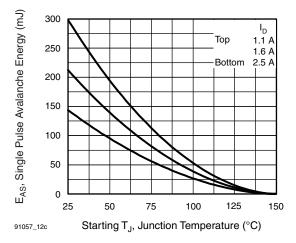


Fig. 15 - Maximum Avalanche Energy vs. Drain Current

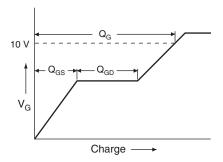


Fig. 16 - Basic Gate Charge Waveform



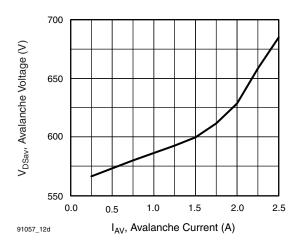


Fig. 17 - Typical Drain-to-Source Voltage vs. Avalanche Current

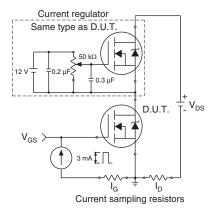


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit

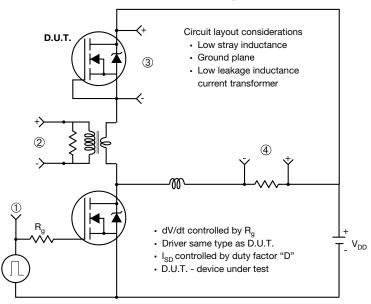




Fig. 19 - For N-Channel

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